STEP - Edge Profile

SEMICON West 06 - Marriott /Moscone

Wedensday, July 12, 2006, 8:00 a.m. - Noon PDT

Meeting Room - Golden Gate C2

Moderator: Win Baylies

AGENDA

				Time
A.	**WELCOME / ANNOUNCMENTS**		8:00 AM	
	Introductions and Announcements	Baylies / BayTech	8:00 AM	0:05
B.	**KEYNOTE ADDRESS**		8:05 AM	0:00
	Wafer-Edge Challenges	Fukuda / SEMI Japan (Fujitsu)	8:05 AM	0:25
C.	**EDGE PROFILE ISSUES**		8:30 AM	0:00
	1) Wafer Maker Issues	Andrukhiv / Komatsu	8:30 AM	0:20
	2) Edge Profile Creation / Subsurface Damage Issues	Riva / Accretech-USA	8:50 AM	0:20
	3) Edge Metrology Issues	Akiyama / Raytex Nakai / Kobelco	9:10 AM	0:20
	4) Edge Profile Parameters	Becker / KoCos	9:30 AM	0:20
	5) Wafer-Edge Descriptions in Defect Detection	Godwin / ISMI	9:50 AM	0:20
	6) Standards	Poduje / ADE	10:10 AM	0:10
D.	**COFFEE BREAK**		10:20 AM	0:20
E.	**EP STANDARDS WG ACTIVITY**		10:40 AM	0:00
	1) Edge Profile Pilot Study	Baylies / BayTech	10:40 AM	0:15
	2) Edge Profile - User Survey	Yoshise / ADE Japan	10:55 AM	0:15
	3) Follow-on Actions	Hughes / MEMC	11:10 AM	0:10
F.	**ROUND TABLE**		11:20 AM	0:00
	Open Discussion	Speakers & Passek/Sitlronic	11:20 AM	0:30
F.	**WRAP-UP**		11:50 AM	0:00
		Hughes & Baylies	11:50 AM	0:10
	ADJOURN		12:00 PM	